



Material Content Data Sheet



Sales Product Name	TLE7186F			Issued		28. August 2013		
MA#	MA000914434							
Package	PG-VQFN-48-14			Weight*		214.02 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	5.659	2.64	2.64	26443	26443
leadframe	inorganic material	phosphorus	7723-14-0	0.032	0.01		148	
	non noble metal	zinc	7440-66-6	0.127	0.06		593	
	non noble metal	iron	7439-89-6	2.537	1.19		11853	
	non noble metal	copper	7440-50-8	103.000	48.13	49.39	481274	493868
wire	noble metal	gold	7440-57-5	2.498	1.17	1.17	11673	11673
encapsulation	organic material	carbon black	1333-86-4	0.467	0.22		2182	
	plastics	epoxy resin	-	14.474	6.76		67632	
	inorganic material	silicondioxide	60676-86-0	78.441	36.65	43.63	366523	436337
leadfinish	non noble metal	tin	7440-31-5	4.336	2.03	2.03	20262	20262
plating	noble metal	silver	7440-22-4	0.663	0.31	0.31	3097	3097
glue	plastics	epoxy resin	-	0.285	0.13		1331	
	noble metal	silver	7440-22-4	1.496	0.70	0.83	6989	8320
*deviation	< 10%	Sum in total:			100,00		1000000	

Important Remarks:

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